# Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers

**Marketing Name / Model**
[List multiple models if applicable.]

| HP ProDesk 600 G5 MT |

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>250W EPA92 Acbel</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink,</td>
<td>Include the cartridges, print heads, tubes, vent</td>
<td></td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](#).
including liquids, semi-liquids (gel/paste) and toner chambers, and service stations.

Components and waste containing asbestos

Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>T-15</td>
</tr>
<tr>
<td>Micro shear</td>
<td>170II</td>
</tr>
<tr>
<td>Screwdriver</td>
<td>PH1</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Pull the latch and remove access panel.
2. Pull the HDD latch from HDD cage.
3. Disconnect SATA/Power cables from the HDD.
4. Disconnect SATA/Power cables from slim ODD.
5. Remove main bezel from chassis
6. Remove HDD cage from the chassis
7. Press slim ODD latch
8. Remove slim ODD from ODD cage
9. Disconnect HDD SATA cable from the MB.
10. Disconnect HDD Power cable from the MB
11. Disconnect P1 Power cable from the MB
12. Disconnect P2 Power cable from the MB.
13. Disconnect speaker cable from the MB.
14. Disconnect CPU power cable from the MB.
15. Disconnect ODD power cable from the MB.
16. Disconnect ODD SATA cable from the MB.
17. Poke clip and remove SATA & power cables.
18. Disconnect heat sink cable from the MB.
19. Disconnect system fan cable from the MB.
20. Use T-15 screwdriver to loose the screws and remove heat sink.
21. Use PH1 screwdriver to loose the screws and remove the fan.
22. Separate the fan from CPU heat sink.
23. Disconnect memory from the MB.
24. Rotate the handle and open it up.
25. Remove CPU from MB.
26. Remove the battery from the MB.
27. Use T-15 to loose the screws of MB.
28. Remove MB from chassis.
29. Use PH1 screwdriver to loose screws of system fan and remove it.
30. Use T-15 screwdriver to loose the screws of speaker and remove it.

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31. Use 170II micro shear to cut two cable ties of PSU cables from chassis
32. Use T-15 screwdriver to loose the screws of PSU
33. Press PSU latch and remove it
34. Cut the cable tie
35. Remove screw for bottom
36. Remove screw for top
37. Remove cover
38. Remove FG screw
39. Disconnect fan connector and inlet connector.
40. Heat the solder of Electrolytic Capacitors greater than 2.5cm in diameter or height and remove it.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Figure 1 Pull the latch and remove access panel
Figure 2 Pull the HDD latch from HDD cage
Figure 3 Disconnect SATA/Power cables from the HDD
Figure 4 Disconnect SATA/Power cables from slim ODD
Figure 5 Remove main bezel from chassis
Figure 6 Remove HDD cage from the chassis
<table>
<thead>
<tr>
<th>Figure 7 Press slim ODD latch</th>
<th>Figure 8 Remove slim ODD from ODD cage</th>
</tr>
</thead>
<tbody>
<tr>
<td><img src="image1.png" alt="Image" /></td>
<td><img src="image2.png" alt="Image" /></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Figure 9 Disconnect HDD SATA cable from the MB</th>
<th>Figure 10 Disconnect HDD Power cable from the MB</th>
</tr>
</thead>
<tbody>
<tr>
<td><img src="image3.png" alt="Image" /></td>
<td><img src="image4.png" alt="Image" /></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Figure 11 Disconnect P1 Power cable from the MB</th>
<th>Figure 12 Disconnect P2 Power cable from the MB</th>
</tr>
</thead>
<tbody>
<tr>
<td><img src="image5.png" alt="Image" /></td>
<td><img src="image6.png" alt="Image" /></td>
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</tbody>
</table>

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Figure 13 Disconnect speaker cable from the MB

Figure 14 Disconnect CPU power cable from the MB

Figure 15 Disconnect ODD power cable from the MB

Figure 16 Disconnect ODD SATA cable from the MB

Figure 17 Poke clip and remove SATA & power cables

Figure 18 Disconnect heat sink cable from the MB
| Figure 19 | Disconnect system fan cable from the MB |
| Figure 20 | Use T-15 screwdriver to loosen the screws and remove heat sink |
| Figure 21 | Use PH1 screwdriver to loosen the screws and remove the fan |
| Figure 22 | Separate the fan from CPU heat sink |
Figure 23 Disconnect memory from the MB

Figure 24 Rotate the handle and open it up

Figure 25 Remove CPU from MB

Figure 26 Remove the battery from the MB

Figure 27 Use T-15 to loose the screws of MB

Figure 28 Remove MB from chassis

PSG instructions for this template are available at EL-MF877-01
| Figure 29 | Use PH1 screwdriver to loosen screws of system fan and remove it |
| Figure 30 | Use T-15 screwdriver to loosen the screws of speaker and remove it |
| Figure 31 | Use 170II micro shear to cut two cable ties of PSU cables from chassis |
| Figure 32 | Use T-15 screwdriver to loosen the screws of PSU |

PSG instructions for this template are available at **EL-MF877-01**
Figure 33 Press PSU latch and remove it

Figure 34 Cut the cable tie

Figure 35 Remove screw for bottom

Figure 36 Remove screw for top

Figure 37 Remove cover

Figure 38 Remove FG screw
Figure 39 Disconnect fan connector and inlet connector.

Figure 40 Remove PCB1 screw

Figure 41 Remove AC inlet & Fan screw

Figure 42 Heat the solder of Electrolytic Capacitors greater than 2.5cm in diameter or height and remove it.